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Product Summary (@ T_A = +25°C)

V _{RRM} (V)	I _o (A)	V _F Max (V) @ +25°C	I _R Max (mA) @ +25°C
200	10	0.88	0.1

Description & Applications

Packaged in the compact thermally efficient PowerDI[®]5 package, provides low V_F and low reverse leakage at high temperatures.

It is ideal for use in the following applications:

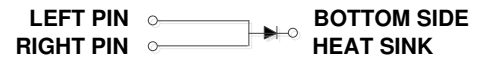
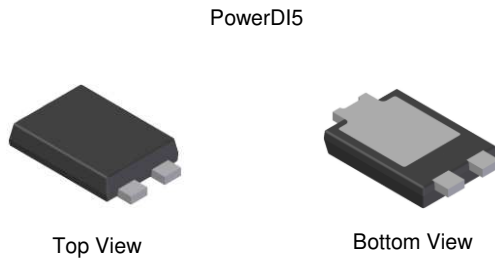
- Bridge Diodes
- Freewheeling Diodes
- Blocking Diodes
- Reverse Protection Diodes

Features and Benefits

- Ultra Low Forward Voltage Drop
- Excellent High Temperature Stability
- Patented Super Barrier Rectifier Technology
- Soft, Fast Switching Capability
- +175°C Operating Junction Temperature
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **An Automotive-Compliant Part is Available Under Separate Datasheet ([SBR10U200P5Q](#))**

Mechanical Data

- Case: PowerDI5
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 [Ⓢ]
- Polarity: See Diagram
- Weight: 0.093 grams (Approximate)

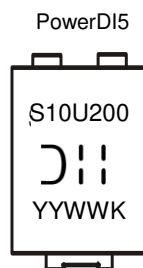


Note: Pins Left & Right must be electrically connected at the printed circuit board.

Ordering Information (Note 4)

Part Number	Case	Packaging
SBR10U200P5-13	PowerDI5	5,000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information


S10U200 = Product Type Marking Code
 D11 = Manufacturers' Code Marking
 YYWW = Date Code Marking
 YY = Last Two Digits of Year (ex: 16 for 2016)
 WW = Week Code (01 to 53)
 K = Factory Designator

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	200	V
Working Peak Reverse Voltage	V_{RWM}		
DC Blocking Voltage	V_{RM}		
Average Rectified Output Current	I_O	10	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	180	A
Repetitive Peak Avalanche Power (1 μs , +25 $^\circ\text{C}$)	P_{ARM}	3,000	W

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	$R_{\theta JA}$	70	$^\circ\text{C/W}$
Typical Thermal Resistance Junction to Case (Note 5)	$R_{\theta JC}$	14	$^\circ\text{C/W}$
Typical Thermal Resistance Junction to Ambient (Note 6)	$R_{\theta JA}$	20	$^\circ\text{C/W}$
Typical Thermal Resistance Junction to Case (Note 6)	$R_{\theta JC}$	3	$^\circ\text{C/W}$
Operating Temperature Range Reverse Mode DC Forward Mode (Note 7)	T_J	-65 to +175 ≤ 200	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-65 to +175	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V_F	—	0.75	0.82	V	$I_F = 5\text{A}$, $T_J = +25^\circ\text{C}$
		—	0.62	0.67		$I_F = 5\text{A}$, $T_J = +125^\circ\text{C}$
		—	0.83	0.88		$I_F = 10\text{A}$, $T_J = +25^\circ\text{C}$
Leakage Current (Note 8)	I_R	—	—	0.1	mA	$V_R = 200\text{V}$, $T_J = +25^\circ\text{C}$
		—	0.18	10		$V_R = 200\text{V}$, $T_J = +125^\circ\text{C}$

- Notes:
5. Device mounted on FR-4 PCB with minimum recommended pad layout per <http://www.diodes.com/package-outlines.html>.
 6. Device mounted on FR-4 PCB with 1-inch pad layout and additional HK2 (45mm x 20mm x 12mm).
 7. Max junction temperature guaranteed for 2 hours.
 8. Short duration pulse test used to minimize self heat effect.

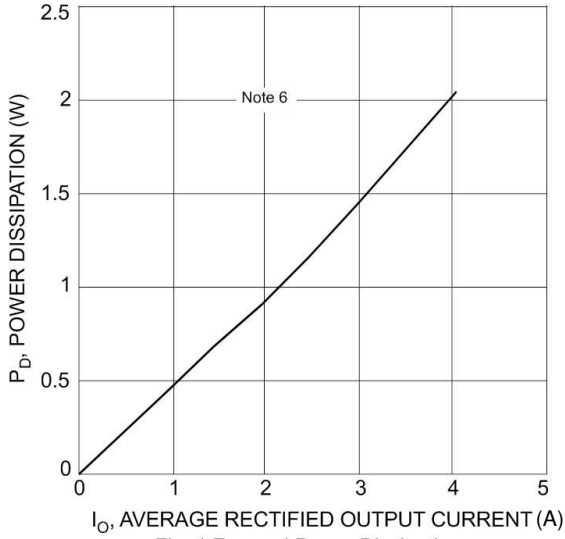


Fig. 1 Forward Power Dissipation

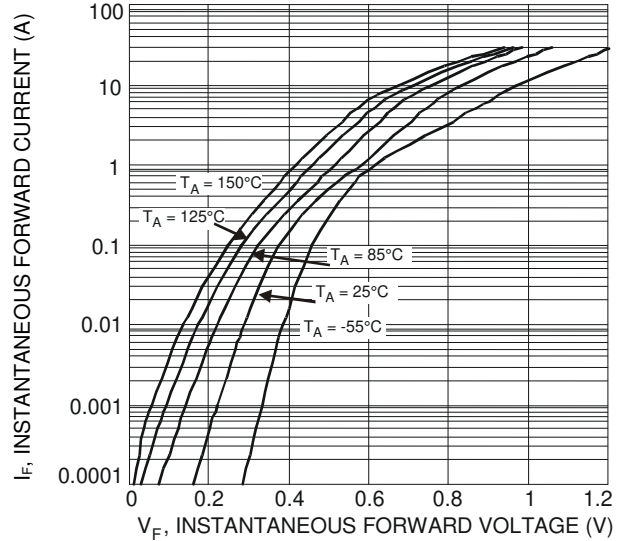


Fig. 2 Typical Forward Characteristics

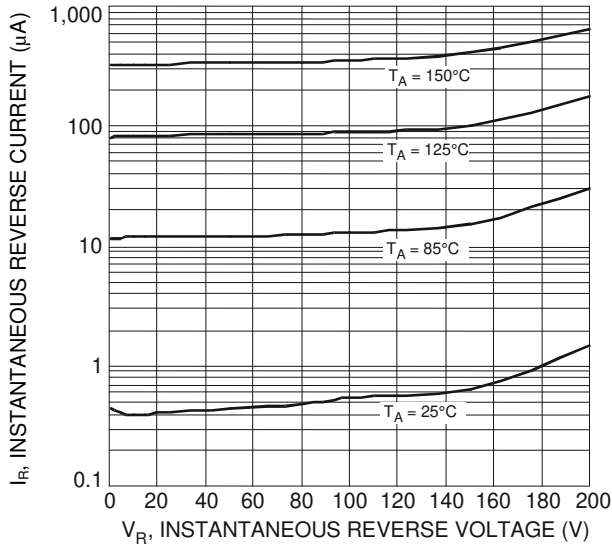


Fig. 3 Typical Reverse Characteristics

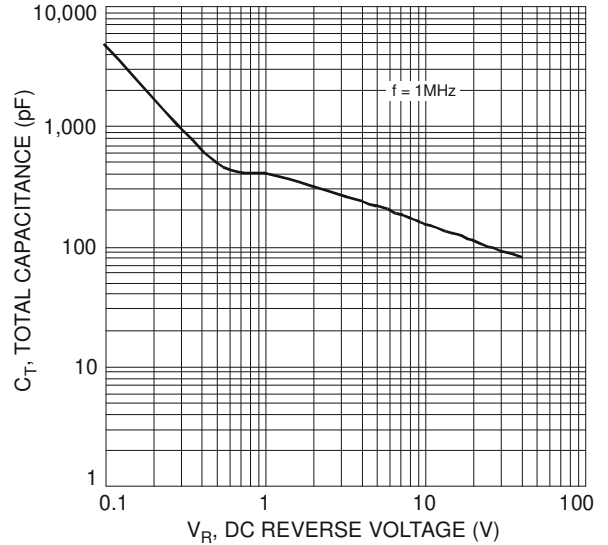


Fig. 4 Total Capacitance vs. Reverse Voltage

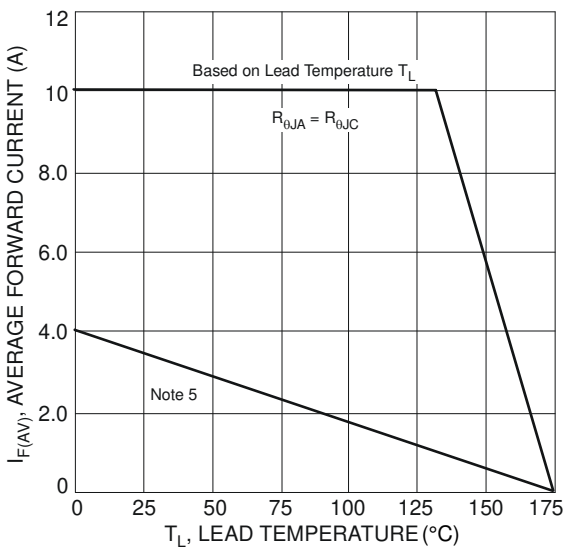


Fig. 5 Forward Current Derating Curve

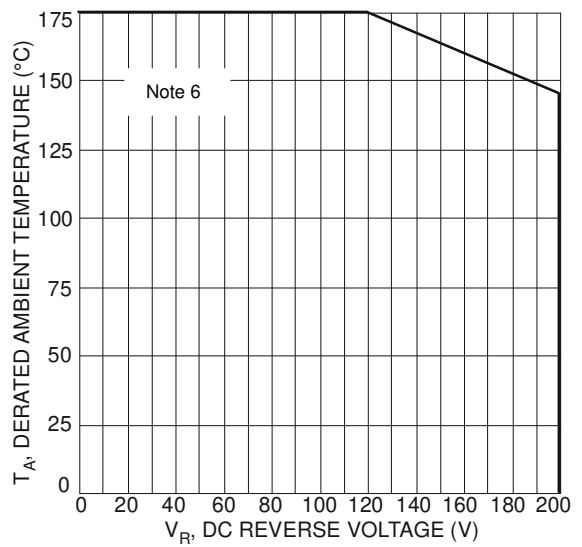


Fig. 6 Operating Temperature Derating

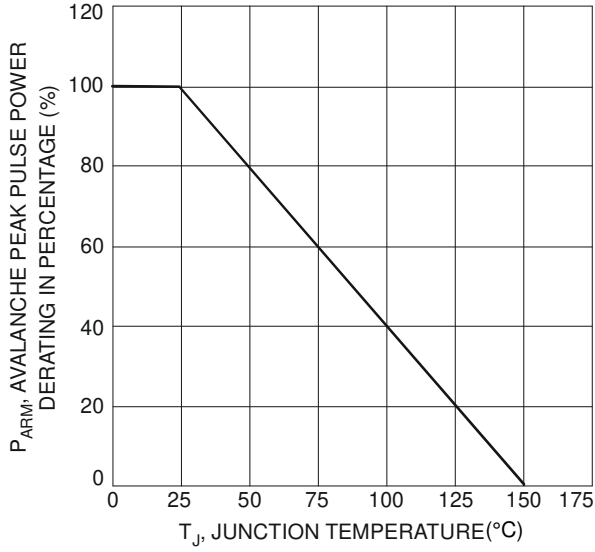


Fig. 7 Pulse Derating Curve

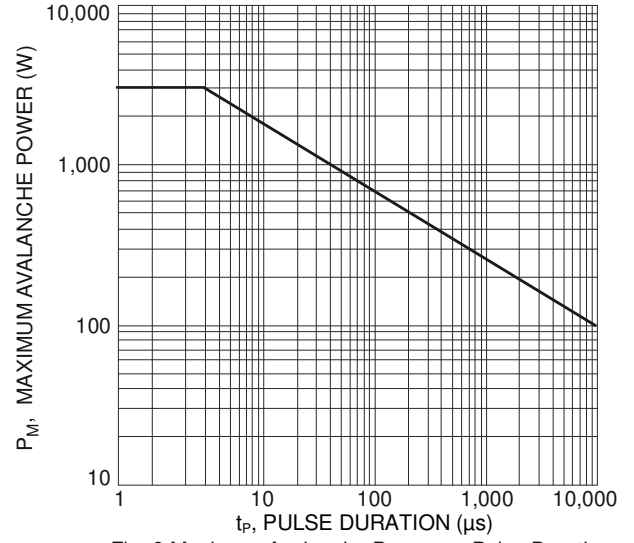
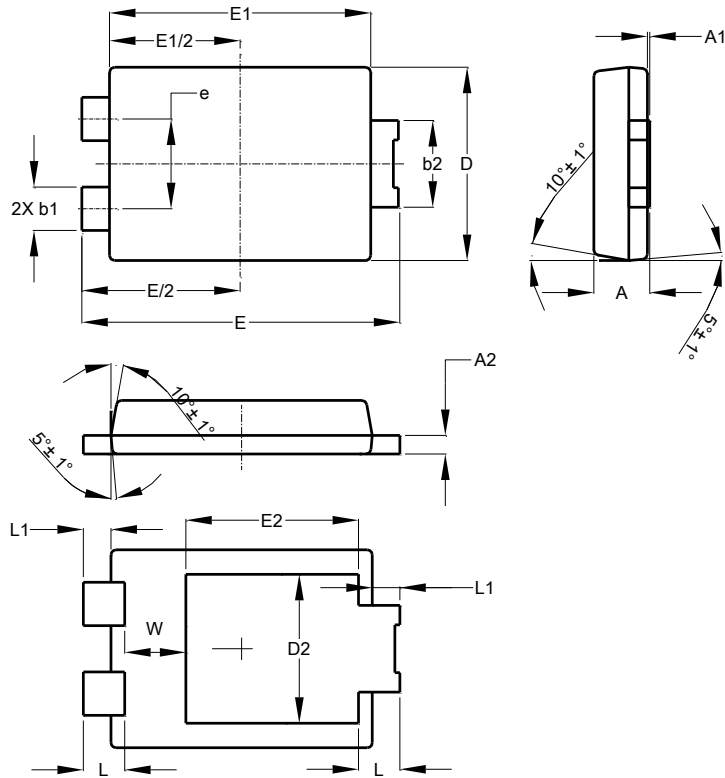


Fig. 8 Maximum Avalanche Power vs. Pulse Duration

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI5

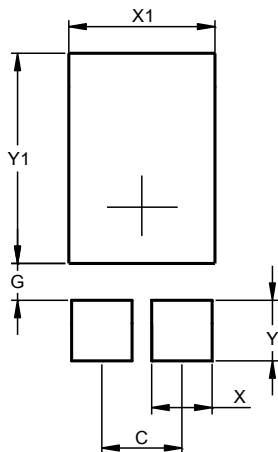


PowerDI5			
Dim	Min	Max	Typ
A	1.05	1.15	1.10
A1	0.00	0.05	--
A2	0.33	0.43	0.381
b1	0.80	0.99	0.89
b2	1.70	1.88	1.78
D	3.90	4.05	3.966
D2	--	--	3.054
E	6.40	6.60	6.504
e	--	--	1.84
E1	5.30	5.45	5.37
E2	--	--	3.549
L	0.75	0.95	0.85
L1	0.50	0.65	0.57
W	1.10	1.41	1.255
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI5



Dimensions	Value (in mm)
C	1.840
G	0.852
X	1.390
X1	3.360
Y	1.400
Y1	4.860

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